

2SK1957

Silicon N Channel MOS FET

REJ03G0988-0200

(Previous: ADE-208-1336)

Rev.2.00 Sep 07, 2005

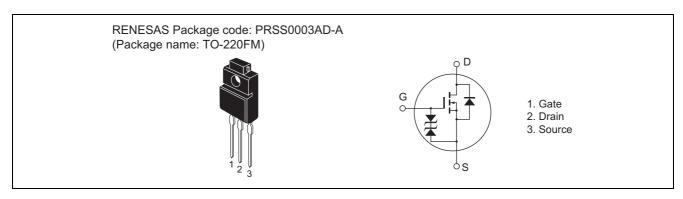
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter, motor control

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	200	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	7	А
Drain peak current	I _{D(pulse)} *1	28	А
Body to drain diode reverse drain current	I _{DR}	7	А
Channel dissipation	Pch* ²	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25°C

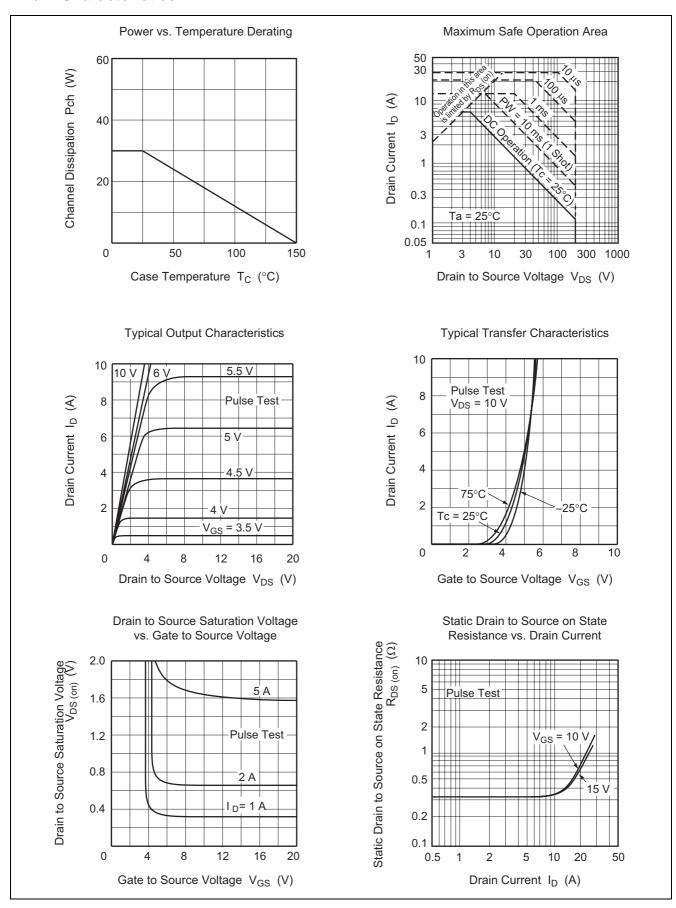
Electrical Characteristics

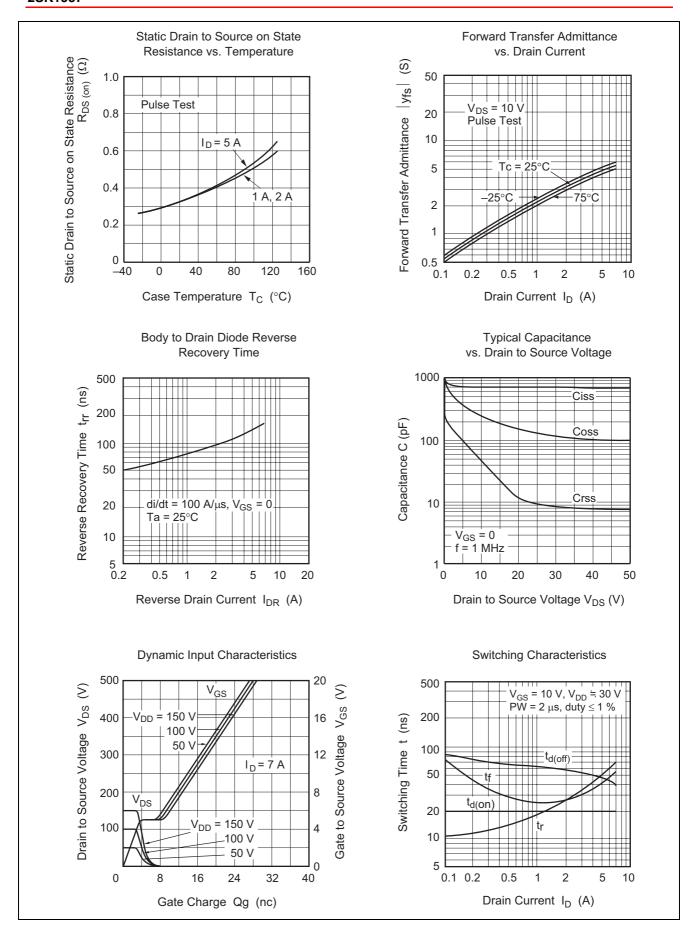
 $(Ta = 25^{\circ}C)$

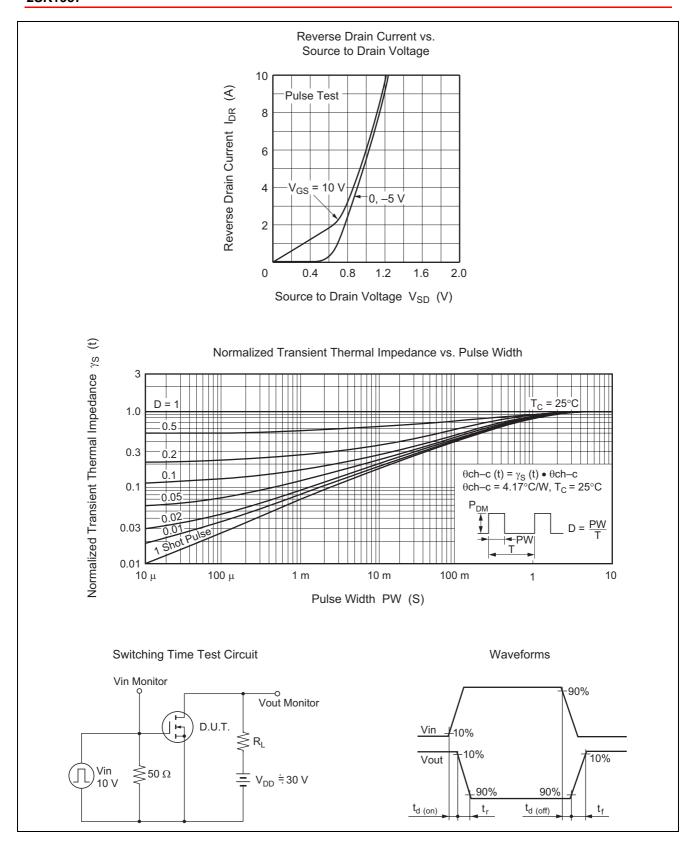
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	200	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$
Gate to source leak current	I_{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	250	μΑ	$V_{DS} = 160 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	4.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R _{DS(on)}	_	0.33	0.45	Ω	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
Forward transfer admittance	y _{fs}	3.0	4.5	_	S	$I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	_	700	1	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	260	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	45	_	pF	
Turn-on delay time	t _{d(on)}	_	20	_	ns	$I_D = 4 A$, $V_{GS} = 10 V$,
Rise time	t _r	_	45	_	ns	$R_L = 7.5 \Omega$
Turn-off delay time	t _{d(off)}	_	50	_	ns	
Fall time	t _f	_	35	_	ns	
Body to drain diode forward voltage	V_{DF}	_	1.1	_	V	I _F = 7 A, V _{GS} = 0
Body to drain diode reverse recovery time	t _{rr}	_	150		ns	$I_F = 7 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note: 3. Pulse Test

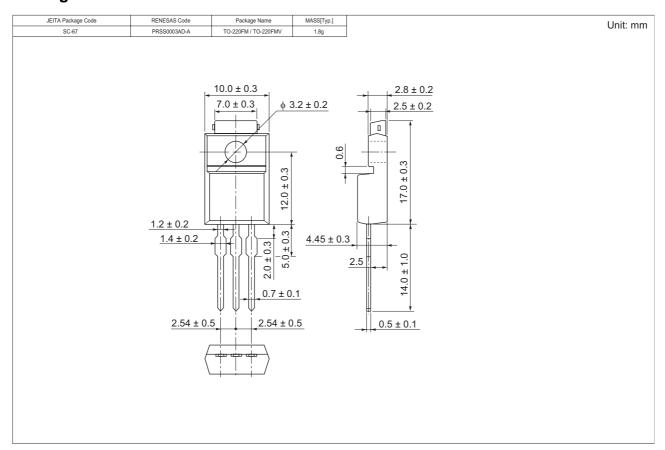
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK1957-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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